## WHAT IS CLAIMED IS:

	1. A surface acoustic wave (SAW) device, comprising:
2	a piezoelectric substrate;
3	a conductive layer located over said piezoelectric substrate;
4	and
5	a resistive layer, interposing a portion of said conductive
6	layer and said piezoelectric substrate, that forms a return path
7	for static charge migrating from said piezoelectric substrate to
all lives teap leads	said conductive layer.
D histor than than	2. The SAW device as recited in Claim 1 wherein said
<u>1</u> 2	piezoelectric substrate comprises one selected from the group
<u>1</u> 3	consisting of:
* 4	bismuth germanium oxide,
<u>-</u> 5	gallium arsenide,
6	lithium borate,
7	lithium niobate,
8	lithium tantalate,
9	langasite,
10	lead zirconium tantalate, and
11	quartz.

	:	3. '	The	SAW	device	as	recited	in C	laim	1 wh	nerein	said
2	condu	ctive	laye	er co	omprises	one	selected	from	the	group	consi	sting
3	of:											
4	ć	aluminum,										
5	Ó	copper,										
6	Ç	gold,										
7	:	silver,										
8	]	platinum, and										
9	]	palladium.										
1. 1. 1. 1. 1. 1. 1. 1. 1. 1. 1. 1. 1. 1							recited selected					
4 4 5 5 6 A 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	of:	silic titan zirco	on, ium, nium,					TIOM		<b>310</b> 4p	COLLET	Scing
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44 44 55 77 8	of:	silic titan zirco hafni vanad	on, ium, nium, um, ium,					TIOM		<b>310</b> 4p	COLLET	Scing
44 4 55 6 7 8 9	of:	silic titan zirco hafni vanad niobi	on, ium, nium, um, ium,					TIOM		<b>310</b> 4p	COLLET	
4 5 5 6 7 8 9 10	of:	silic titan zirco hafni vanad niobi tanta	on, ium, nium, um, ium, um,							310ap	COLLET	
44 4 55 6 7 8 9	of:	silic titan zirco hafni vanad niobi	on, ium, nium, um, ium, um,							31 Out	COLLET	

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- The SAW device as recited in Claim 1 wherein said resistive layer couples a selected signal pad to one of a plurality of ground pads.
  - 6. The SAW device as recited in Claim 1 wherein said resistive layer is interposed between an entirety of a pad portion of said conductive layer and said piezoelectric substrate.
  - The SAW device as recited in Claim 1 wherein said SAW device comprises two signal pads and four ground pads and said resistive layer is divided into portions that span said two signal pads and said four ground pads.

- 8. A method of manufacturing a surface acoustic wave (SAW) device, comprising:

  providing a piezoelectric substrate;

  forming a conductive layer over said piezoelectric substrate;
- creating a resistive layer between a portion of said conductive layer and said piezoelectric substrate, said resistive layer forming a return path for static charge migrating from said piezoelectric substrate to said conductive layer.
  - 9. The method as recited in Claim 8 wherein said piezoelectric substrate comprises one selected from the group consisting of:

bismuth germanium oxide,

gallium arsenide,

lithium borate,

7 lithium niobate,

8 lithium tantalate,

9 langasite,

10 lead zirconium tantalate, and

11 quartz.

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and

4 copper,

5 gold,

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6 silver,

7 platinum, and

palladium.

11. The method as recited in Claim 8 wherein said resistive layer comprises one selected from the group consisting of:

silicon,

titanium,

zirconium,

hafnium,

vanadium,

8 niobium,

9 tantalum,

10 molybdenum,

11 tungsten,

12 chromium,

13 nitrides thereof, and

14 carbides thereof.

12. The method as recited in Claim 8 wherein said creating comprises coupling said resistive layer between a selected signal pad and one of a plurality of ground pads.

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- 13. The method as recited in Claim 8 wherein said creating comprises creating said resistive layer between an entirety of a pad portion of said conductive layer and said piezoelectric substrate.
  - 14. The method as recited in Claim 8 wherein said SAW device comprises two signal pads and four ground pads and said resistive layer is divided into portions that span said two signal pads and said four ground pads.

- 15. A surface acoustic wave (SAW) filter, comprising:
- 2 a piezoelectric substrate;
- 3 a conductive layer located over said piezoelectric substrate
- 4 and forming a network of cooperating SAW devices; and
- 5 a resistive layer, interposing a portion of said conductive
- 6 layer and said piezoelectric substrate, that forms a return path
- 7 for static charge migrating from said piezoelectric substrate to
- 8 said conductive layer.

[]] []7 16. The SAW filter as recited in Claim 15 wherein said piezoelectric substrate comprises one selected from the group consisting of:

bismuth germanium oxide,

gallium arsenide,

lithium borate,

lithium niobate,

- 8 lithium tantalate,
- 9 langasite,
- 10 lead zirconium tantalate, and
- 11 quartz.

- 17. The SAW filter as recited in Claim 15 wherein said 2 conductive layer comprises one selected from the group consisting 3 of: aluminum, 4 5 copper, 6 gold, silver, 7 platinum, and 8 9 palladium. The state of the state of the state of things of the state of the stat The SAW filter as recited in Claim 15 wherein said 18. resistive layer comprises one selected from the group consisting
  - of:

silicon, **\_**5 titanium, 17 <u>\_</u>16 zirconium, mà

7 hafnium,

vanadium, 8

niobium, 9

tantalum, 10

11 molybdenum,

12 tungsten,

chromium, 13

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carbides thereof.

- 19. The SAW filter as recited in Claim 15 wherein said
  2 resistive layer couples a selected signal pad to one of a plurality
  3 of ground pads.
  - 20. The SAW filter as recited in Claim 15 wherein said resistive layer is interposed between an entirety of a pad portion of said conductive layer and said piezoelectric substrate.
  - 21. The SAW filter as recited in Claim 15 wherein said SAW device comprises two signal pads and four ground pads and said resistive layer is divided into portions that span said two signal pads and said four ground pads.